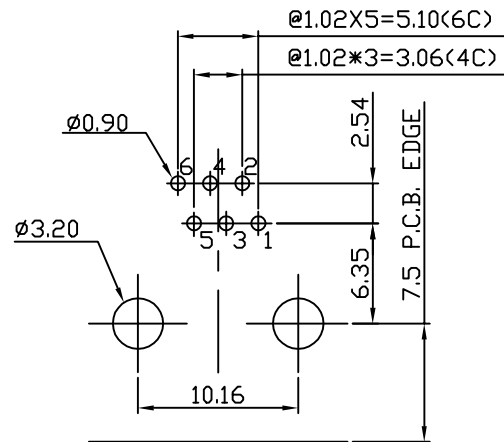
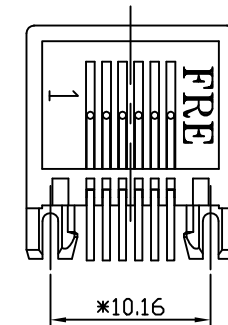
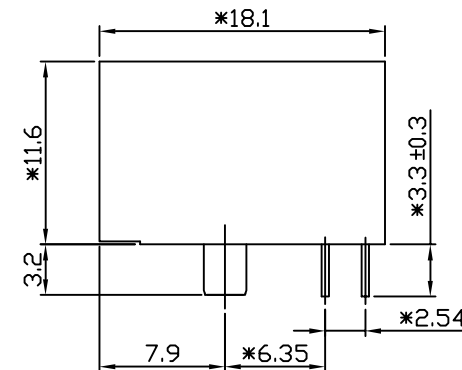
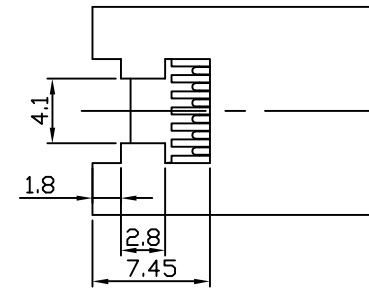
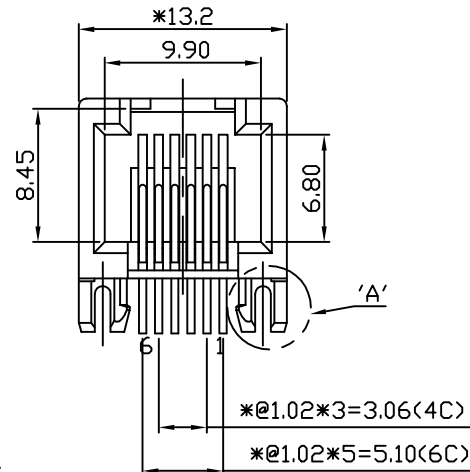


REVISION RECORD				
REV	ECD	DESCRIPTION	DRFT	CHKD
△		ADD P\N.	CXG 03/05/05	



PCB Thickness=1.60mm

PC Board Layout Component Side Shown

**NOTES:****ELECTRICAL:**

1. VOLTAGE RATING : 150 VAC RMS.
2. CURRENT RATING : 1.5 AMP.
3. CONTACT RESISTANCE : 20 MILLIOHMS MAX.
4. INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 500 VDC.
5. DIELECTRIC STRENGTH : 1000 VAC RMS 60Hz, 1MIN.

MECHANICAL:

1. HOUSING MATERIAL : NYLON+30%G.F UL94V-0.
2. CONTACT MATERIAL : PHOSPHOR BRONZE 0.46mm.
3. PLATING : GOLD PLATING OVER NICKEL.
4. OPERATING LIFE : 750 CYCLES MIN.
5. PCB RETENTION PRE-SOLDER : 1 LB MIN.
6. PCB RETENTION POST-SOLDER: 10 LBS MIN.

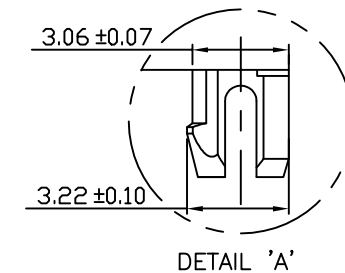
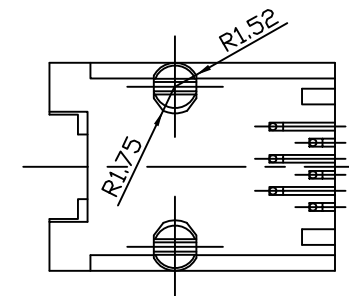
ENVIRONMENTAL:

1. STORAGE : -40°C TO +85°C.
2. OPERATION: -20°C TO 85°C.
3. WAVE SOLDER TEMPERATURE: 255-265°C (5-10 SECOND).

MATES WITH MODULAR PLUG CONFORMING TO
FCC PART 68, SUBPART F.

ROHS PART NUMBER: E536X-300XXX-L

△ 2- 2C 1- 3u" 2- 6u" 3-15u"
4- 4C 4-30u" 5-50u"
6- 6C
6G-GREEN
VG-GREY



DETACHED LISTS		MM (INCH)		DFTD SAMMY		DATE 03/16/05		FULL RISE ELECTRONIC CO., LTD	
TOLERANCES EXCEPT AS NOTED		CHKD		DATE		TITLE		11.5mm SIDE PCB JACK 6P	
MM		MFD		DATE		DRAWING NO. GE533A42-LA		SIZE REV	
.0 ± 0.2		APPLV		XLF		DATE 05/05/05		A3 1	
.00 ± 0.15		MATERIAL		QT'Y		/PART NO. SEE NOTE		DO NOT SCALE DRAWING	
.000 ± 0.075		FINISH		SCALE : 3 : 1		SHEET 1		OF 1	
ANGLES ± 0.5		THIRD ANGLE PROJECTION							